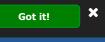
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ARRAYJ-BOB3-16P-GEVK: J-Array 3mm 4x4 BOB

The ArrayJ-BOB3-16P is an evaluation board allowing easy access to the signals from a SensL ArrayJ-300XX-16P, 3 mm 4 x 4 SiPM array. The Breakout Board has two HIROSE 20-way connectors

DF17(3.0)-20DS-0.5v(57). These connectors mate with the Samtec DF17(2.0)-20DP-0.5v(57) board-to-board connectors on the array. All signals on the array are routed via the mating connectors to header pins. These pins are formed by two 20-way (10 x 2 row) 2.54 mm pitch headers.

Three SMA connectors and Balun transformers are provided with 4pin headers to allow any signal to be connected directly to the SMA or via the transformer using jumper wires. Four 7 mm holes are aligned on a 25 mm grid to allow mounting of the board on an optical breadboard.



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